

Amendments to the Claims

Please amend the claims as shown below. This **Listing of Claims** will replace all prior versions, and listings, of claims in the application.

1-11. (Cancelled)

12. (Currently amended) A method for manufacturing a test sensor, comprising:
forming a multiple layer device, including depositing a first metallic layer onto a substrate material by physical vapor deposition; depositing an intermediate, sacrificial layer on said metallic layer; and depositing an electrically non-conductive layer adjacent said intermediate, sacrificial layer by plasma enhanced chemical vapor deposition; and
applying ~~an amount of energy~~ to said multiple layer device an amount of energy ineffective to ablate said electrically non-conductive layer directly, but effective to selectively remove ablate a portion of said intermediate, sacrificial layer, thereby removing said intermediate, sacrificial layer and causing a corresponding portion of ~~either said metallic layer or~~ said non-conductive layer to be removed.

13. (Cancelled)

14. (Previously Presented) The method of claim 12, wherein said amount of energy is in the range of approximately 40 mJ/cm² to 450 mJ/cm².

15. (Previously Presented) The method of claim 12, wherein said energy is provided by an ion-beam.

16. (Previously Presented) The method of claim 12, wherein said energy is provided by an electron beam.

17. (Previously Presented) The method of claim 12, wherein the metallic layer includes at least one of copper, silver, gold, platinum, palladium, nickel, or aluminum.

18. (Previously Presented) The method of claim 12, wherein the electrically non-conductive layer has a thickness less than or substantially equal to 1 μm .

19. (Previously Presented) The method of claim 12, wherein the intermediate, sacrificial layer is made of polytetrafluorethylene.

20. (Previously Presented) The method of claim 19, wherein the intermediate, sacrificial layer is deposited onto said metallic layer by plasma enhanced chemical vapor deposition.

21. (Previously Presented) The method of claim 12, wherein the substrate is made of a polymer material.

22. (Previously presented) The method of claim 21, wherein the substrate is flexible.

23. (Currently amended) The method of claim 12, further comprising:
depositing ~~at least one of~~ a second metallic layer, ~~and a second intermediate, sacrificial layer, or a second non-metallic conductive layer~~ on said multiple layer device and removing said second metallic layer by ablating an intermediate, sacrificial layer.

24. (Cancelled)

25. (Previously Presented) The method of claim 12, further comprising:
performing plasma activation before depositing said metallic layer, said non-conductive layer, or said intermediate layer.

26. (Previously Presented) The method of claim 12, wherein said energy is provided by a laser.

27. (Currently amended) The method of claim 12, wherein the intermediate, sacrificial layer is made of a ~~Teflon-like~~ compound of the formula C_xF_y .

28. (Previously Presented) The method of claim 12, wherein the electrically non-conductive layer is made of a ceramic layer comprising MgO.

29. (Currently amended) The method of claim 12, wherein the electrically non-conductive layer ~~is not suitable for laser ablation~~ comprises one or more members of the group consisting of MgO, SiO, and MgF_2 .